



(1.27 mm) .050"



HIGH-SPEED/HIGH-DENSIT (1) 5 EV = 5

Up to

500 pins

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?SEAF

Insulator Material: Black LCP

Contact Material: Copper Alloy Operating Temp Range:

-55 °C to +125 °C Current Rating (7 mm stack height):

1.8 A per pin (10 adjacent pins powered) Plating:

Au or Šn over 50 μ" (1.27 μm) Ni Contact Resistance:

5.5 mΩ Working Voltage: 240 VA

RoHS Compliant: Lead-Free Solderable:

Yes

Board Mates: SEAM, SEAMP

SEAR, SEAMI

Cable Mates:

Standoffs:

JSO, JSOM

SEAF



(1.15 mm) .045" NOMINAL WIPE I OW insertion/ extraction forces

5, 8 and 10 row footprint compatible with SamArray®. Samples recommended.

Solder

charges

HIGH-SPEED CHANNEL PERFORMANCE

SEAF/SEAM @ 10 mm Mated Stack Height

NO. PINS

PER ROW

Rating based on Samtec reference channel. For full SI performance data visit Samtec.com or contact SIG@samtec.com

PLATING

OPTION

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



STANDARDS

- PISMO 2
- VITA 47
- VITA 57.1

PROTOCOLS

- 100 GbE
- Flbre Channel
- Rapid I/O
- PCI Express[®]
- SATA
- InfiniBand™

MATED HEIGHTS				
SEAM	SEAF LEAD STYLE			
LEAD STYLE	-05.0	-06.0	-06.5	
-02.0	7 mm	8 mm	8.5 mm	
-03.0	8 mm	9 mm	9.5 mm	
-03.5	8.5 mm	9.5 mm	10 mm	
-06.5	11.5 mm	12.5 mm	13 mm	
-07.0	12 mm	13 mm	13.5 mm	
-09.0	14 mm	15 mm	15.5 mm	
-11.0	16 mm	17 mm	17.5 mm	

Notes:

Patented

IPC-A-610F and IPC J-STD-001F Class 3 solder joint.

Some sizes, styles and options are non-standard, non-returnable.



(-10 only available in 04 row)

(-15 only available in 04 or 10 row with -05.0 lead style)

В
(5.66) .223
(8.20) .323
(10.74) .423
(13.28) .523

LEAD STYLE from chart

LEAD

STYLE

= 10 µ" (0.25 µm) Gold on contact area, Matte Tin on

LEAD STYLE	A	
-05.0	(5.05) .199	
-06.0	(6.05) .238	
-06.5	(6.55) .258	

solder tail -S = 30 µ" (0.76 µm) Gold on contact area. Matte Tin on solder tail

-05 =Five Rows -06 =Six

NO. OF

ROWS

Rows

-04 =Four Rows

-2

SOLDER

TYPE

-1

-08 =Eight Rows -10

-LP = Tin/Lead Alloy Solder Charge = Lead-Free Solder Charge

= Latch Post (-LP required for SEAC mate only) (Available with 05.0 lead style and -04, -06, -08 & -10 rows only)

OPTION

= Polyimide film Pick & Place Pad (Not available with -10 and –15 pins with –LP Latch post)

PΔIR

80

60

75

60

45

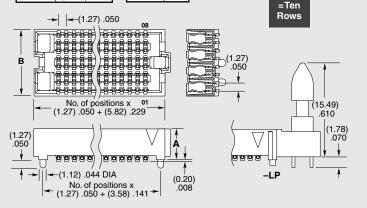
50

40

25

ALSO AVAILABLE (MOQ Required)

· Polarization pin Contact Samtec.



DIFFERENTIAL

